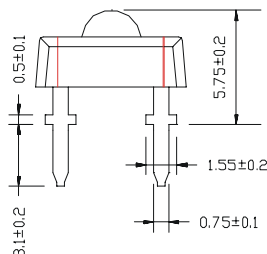
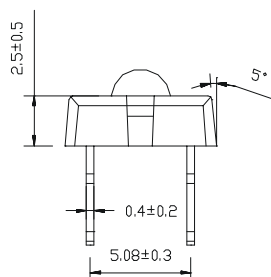
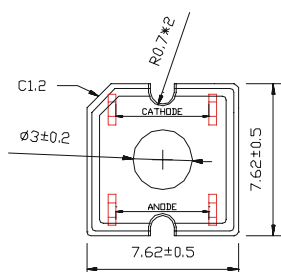


Device Selection Guide

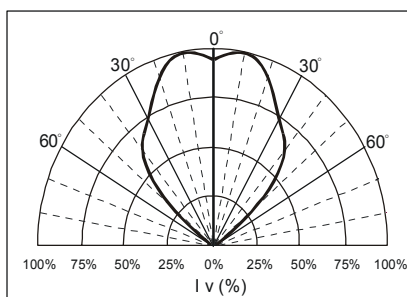
Part Number EOZ-	Total Flux $\Phi_v(\text{mlm}) @ I_F = 50\text{mA}$		Luminous Intensity $I_v(\text{mcd}) / \Phi_v(\text{mlm})$ @ $I_F = 50\text{mA}$	Viewing Angle $2\theta_{1/2}$	Dominant Wavelength $\lambda_D(\text{nm}) @ I_F = 50\text{mA}$	Forward Voltage $V_F(\text{V}) @ I_F = 50\text{mA}$		$I_R(\mu\text{A})$ @ $V_R = 5\text{V}$
	Min.	Typ.	Typ.	Typ.	Typ.	Typ.	Max.	Max.
ZTFRCDD0-GG	2000	2750	0.55	90°	525	4.2	4.8	10

BIN #	D	E	F		
Total Flux (mlm) @ $I_F = 50\text{mA}$	2000-2750	2750-3850	3850-5400		

Package Dimensions



Beam Pattern



Note:

- All dimensions are in millimeter.
- Unspecified tolerance : $\pm 0.20\text{mm}$.
- Protruded resin under bottom surface of epoxy is 1.5mm max.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to be changed without notice.

Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	Symbol	Maximum Value	USER---APPROVED
Average Forward Current	I_F	50mA	
Peak Forward Current ^[a]	I_{peak}	80mA	
Reverse Voltage	V_R	5V	
Power Dissipation	P_D	240mW	
Operating Temperature Range	T_{OPR}	$-40^\circ\text{C} \sim +85^\circ\text{C}$	
Storage Temperature Range	T_{STO}	$-40^\circ\text{C} \sim +100^\circ\text{C}$	
Lead Soldering Temperature	T_{SOL}	$260^\circ\text{C} / 5 \text{ seconds}$	

Notes: [a] Duty Ratio = 1/10, Pulse Width = 0.1ms.

Headquarters

5F, No. 1, Creation Road II, Hsinchu Science Park,
Hsinchu, Taiwan 300, R.O.C.
Tel : 886-3-5679000 Fax : 886-3-5679999
http://www.eoi.com.tw E-mail : Service@eoi.com.tw

U.S. Office

1400 W. Lambert Road, Suite B,
Brea, CA92821, U.S.A
Tel : 1-562-694-1246 Fax : 1-562-691-3087
http://www.eoi-us.com E-mail : Sales@eoius.com

